



# 2PB709ART

45 V, 100 mA PNP general-purpose transistor

Rev. 01 — 19 March 2007

Product data sheet

## 1. Product profile

### 1.1 General description

PNP general-purpose transistor in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

NPN complement: 2PD601ART.

### 1.2 Features

- General-purpose transistor
- Small SMD plastic package

### 1.3 Applications

- General-purpose switching and amplification

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CE0}$	collector-emitter voltage	open base	-	-	-45	V
$I_C$	collector current		-	-	-100	mA
$h_{FE}$	DC current gain	$V_{CE} = -10$ V; $I_C = -2$ mA	210	-	340	

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	base		
2	emitter		
3	collector		

*sym013*

### 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
2PB709ART	-	plastic surface-mounted package; 3 leads	SOT23

### 4. Marking

Table 4. Marking codes

Type number	Marking code <sup>[1]</sup>
2PB709ART	C5*

- [1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

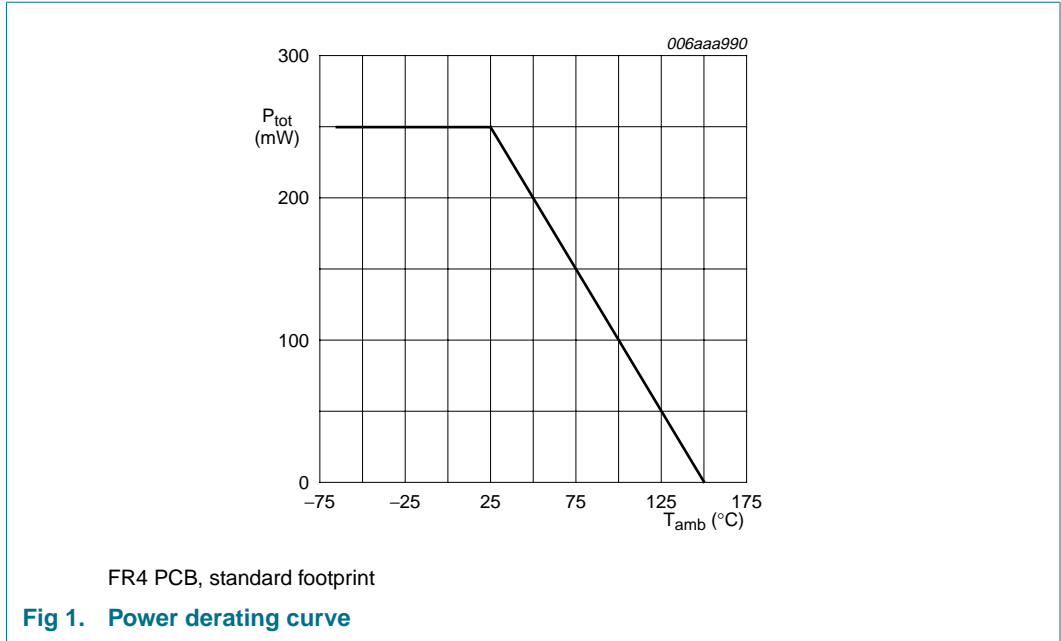
### 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	-45	V
$V_{CEO}$	collector-emitter voltage	open base	-	-45	V
$V_{EBO}$	emitter-base voltage	open collector	-	-6	V
$I_C$	collector current		-	-100	mA
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	-200	mA
$I_{BM}$	peak base current	single pulse; $t_p \leq 1$ ms	-	-100	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	<sup>[1]</sup> -	250	mW
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

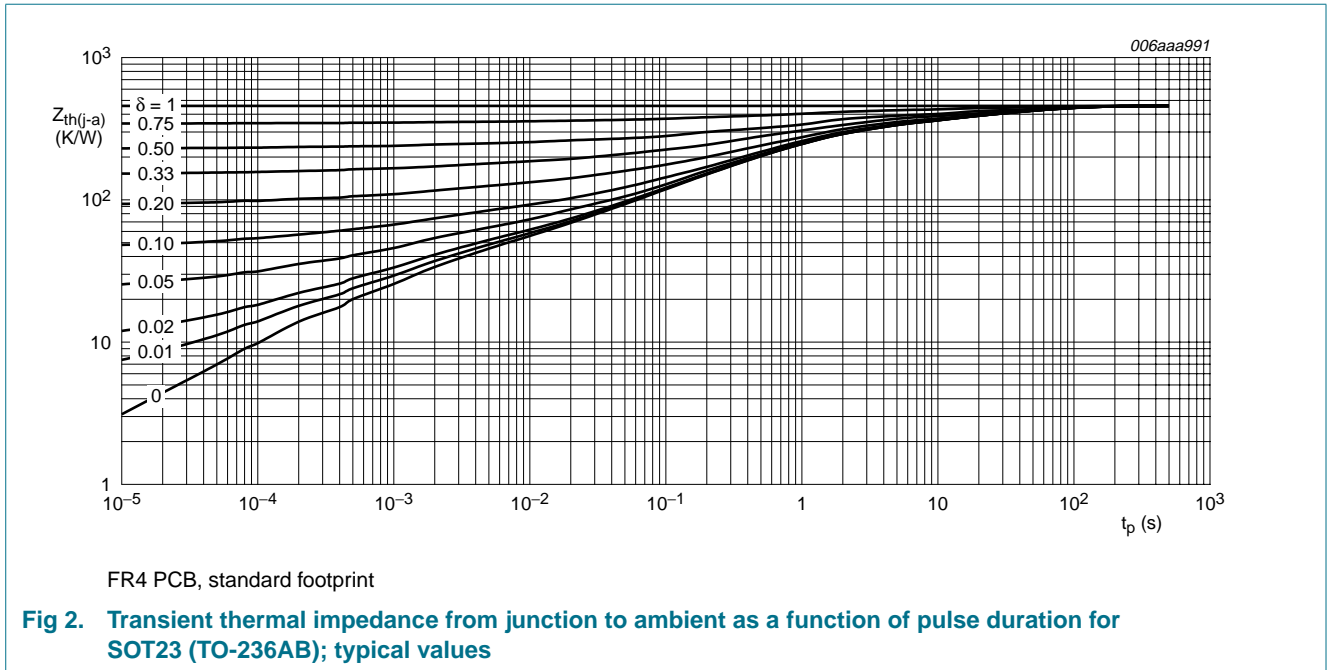


## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1]	-	500	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		-	-	140	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.



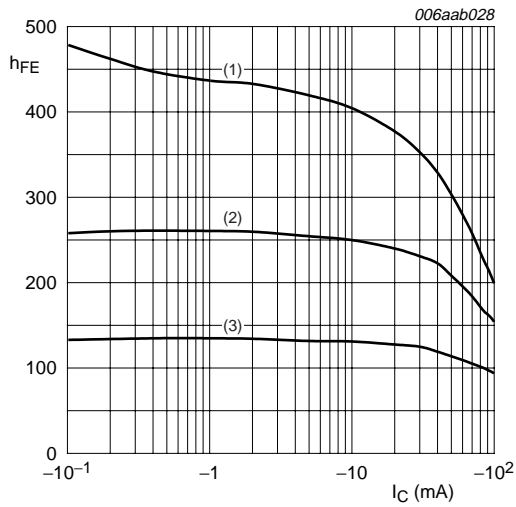
## 7. Characteristics

**Table 7. Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

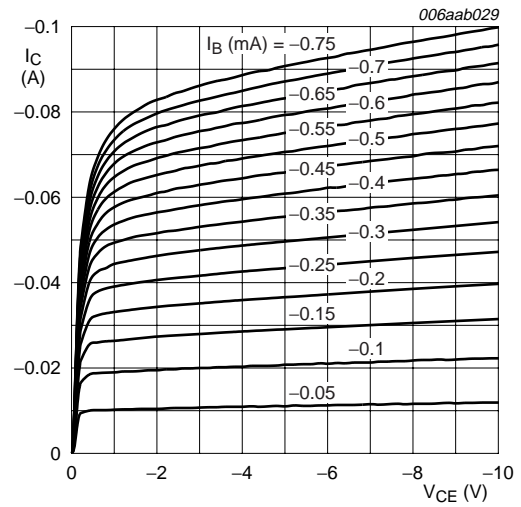
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -45\text{ V}; I_E = 0\text{ A}$	-	-	-10	nA
		$V_{CB} = -45\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	-5	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -5\text{ V}; I_C = 0\text{ A}$	-	-	-10	nA
$h_{FE}$	DC current gain	$V_{CE} = -10\text{ V}; I_C = -2\text{ mA}$	210	-	340	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -100\text{ mA}; I_B = -10\text{ mA}$	[1]	-	-500	mV
$f_T$	transition frequency	$V_{CE} = -10\text{ V}; I_C = -1\text{ mA}; f = 100\text{ MHz}$	70	-	-	MHz
$C_c$	collector capacitance	$V_{CB} = -10\text{ V}; I_E = I_e = 0\text{ A}; f = 1\text{ MHz}$	-	-	5	pF

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .



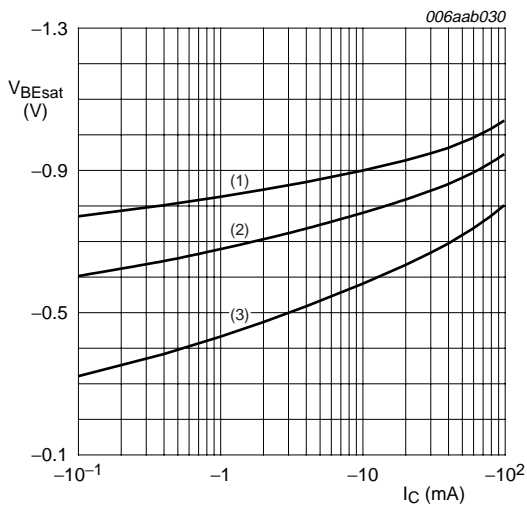
$V_{CE} = -10\text{ V}$   
 (1)  $T_{amb} = 150\text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = -55\text{ }^{\circ}\text{C}$

**Fig 3. DC current gain as a function of collector current; typical values**



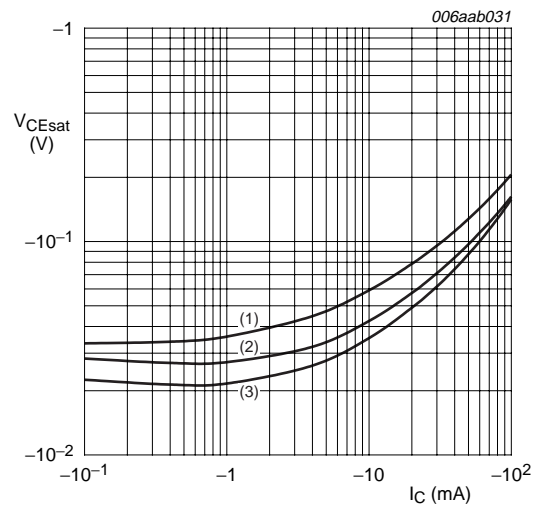
$T_{amb} = 25\text{ }^{\circ}\text{C}$

**Fig 4. Collector current as a function of collector-emitter voltage; typical values**



$I_C/I_B = 10$   
 (1)  $T_{amb} = -55\text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = 150\text{ }^{\circ}\text{C}$

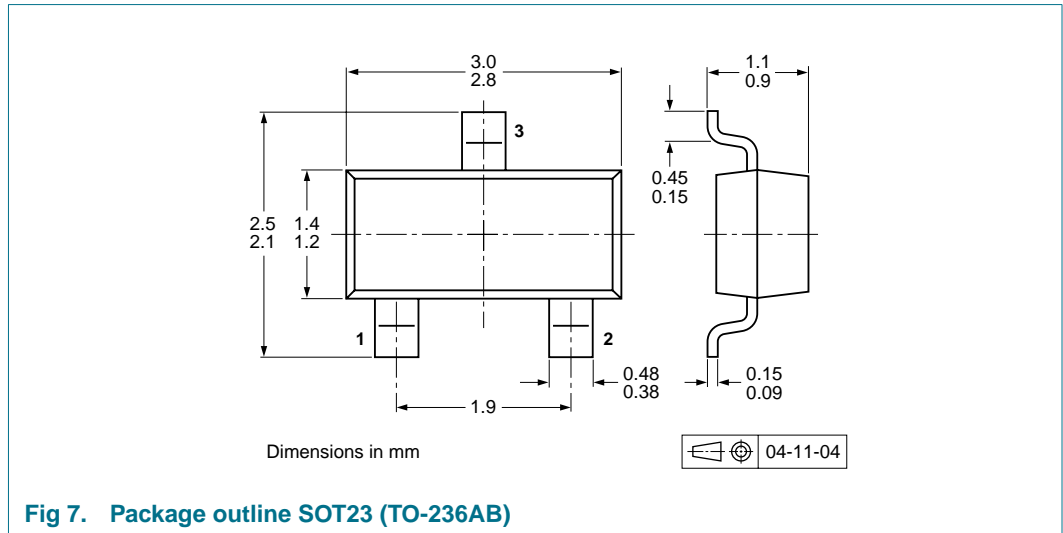
**Fig 5. Base-emitter saturation voltage as a function of collector current; typical values**



$I_C/I_B = 10$   
 (1)  $T_{amb} = 150\text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = -55\text{ }^{\circ}\text{C}$

**Fig 6. Collector-emitter saturation voltage as a function of collector current; typical values**

## 8. Package outline



## 9. Packing information

**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			3000	10000
2PB709ART	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235

[1] For further information and the availability of packing methods, see [Section 13](#).

10. Soldering

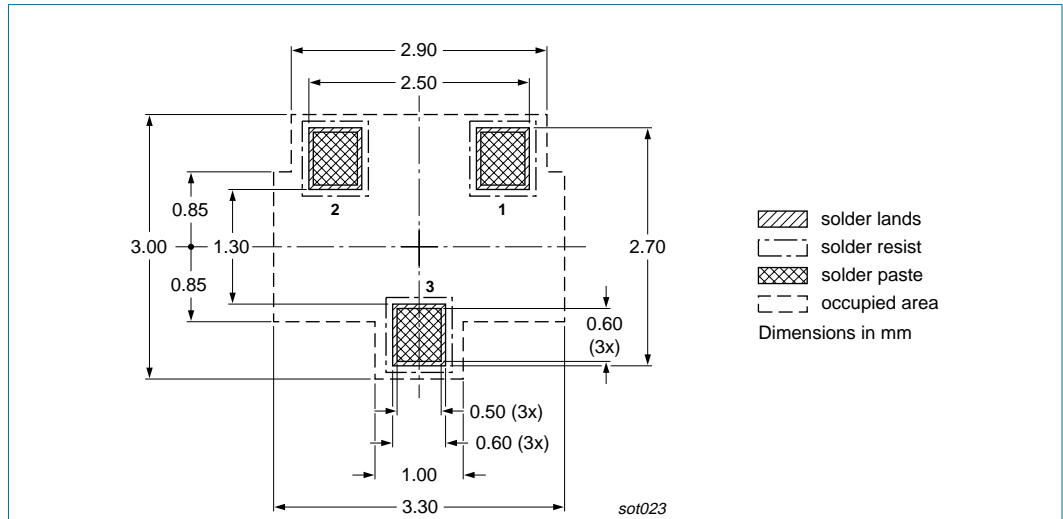


Fig 8. Reflow soldering footprint SOT23 (TO-236AB)

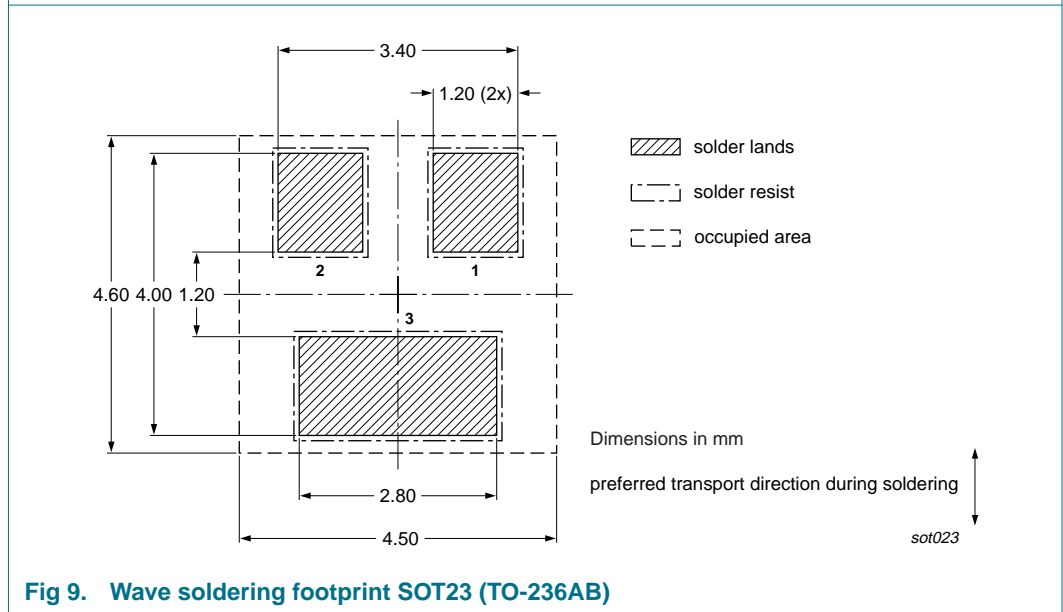


Fig 9. Wave soldering footprint SOT23 (TO-236AB)

## 11. Revision history

**Table 9.** Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
2PB709ART_1	20070319	Product data sheet	-	-



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### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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